

CGHV35400F1

400 W, 2.9 - 3.5 GHz, GaN HEMT

Description

The CGHV35400F1 is a gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically with high efficiency and high gain for the 2.9 - 3.5 GHz S-Band radar band. The device has been developed with long pulse capability to meet the developing trends in radar architectures. The transistor is matched to 50-ohms on the input and 50-ohms on the output. The CGHV35400F1 is based on the high power density 50 V, 0.4 µm GaN on silicon carbide (SiC) manufacturing process. The transistor is supplied in a ceramic/ metal flange package of type 440226.



Package Type: 440226 PNs: CGHV35400F1

Typical Performance Over 2.9 - 3.5 GHz ($T_c = 25^{\circ}$ C)

Parameter	2.9 GHz	3.2 GHz	3.5 GHz	Units
Small Signal Gain ^{1,2}	15.0	13.6	12.5	dB
Output Power ^{1,3}	57.1	56.9	56.4	dBm
Power Gain ^{1,3}	11.1	10.9	10.4	dB
Drain Efficiency ^{1,3}	69	64	60	%

Features

- 500 W Typical P_{SAT}
- >65% Typical Drain Efficiency
- 13 dB Large Signal Gain
- **High Temperature Operation**

Note: Features are typical performance across frequency under 25°C operation. Please reference performance charts for additional details.

Applications

Civil and Military Pulsed **Radar Amplifiers**

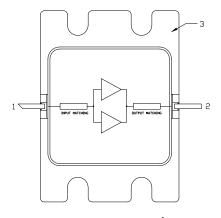


Figure 1.



¹ V_{DD} = 50 V, I_{DQ} = 500 mA 2 Measured at P_{IN} = -20 dBm 3 Measured at P_{IN} = 46 dBm and 2 ms; Duty Cycle = 20%



Absolute Maximum Ratings (not simultaneous) at 25°C

Parameter	Symbol	Rating	Units	Conditions
Drain-source Voltage	V _{DSS}	150	VDC	25°C
Gate-source Voltage	V _{GS}	-10, +2	VDC	25 C
Storage Temperature	T _{STG}	-65, +150	°C	
Maximum Forward Gate Current	I _G	80	mA	25°C
Maximum Drain Current	I _{DMAX}	24	А	
Soldering Temperature	T _s	245	°C	
Junction Temperature	T _J	225		MTTF > 1e6 Hours

Electrical Characteristics (Frequency = 2.9 GHz to 3.5 GHz unless otherwise stated; $T_c = 25^{\circ}$ C)

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions
DC Characteristics						
Gate Threshold Voltage	V _{GS(TH)}	-3.8	-3.0	-2.3	٧	$V_{DS} = 10 \text{ V, I}_{D} = 83.6 \text{ mA}$
Gate Quiescent Voltage	$V_{GS(Q)}$	_	-2.7	_	V_{DC}	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA}$
Saturated Drain Current ¹	I _{DS}	62.7	75.5	_	Α	$V_{DS} = 6.0 \text{ V}, V_{GS} = 2.0 \text{ V}$
Drain-Source Breakdown Voltage	V _{BR(DSS)}	125	_	_	٧	V _{GS} = -8 V, I _D = 83.6 mA
RF Characteristics ²						
Small Signal Gain	S21 ₁	_	13.7	_	dB	P _{IN} = -20 dBm, Freq = 2.9 - 3.5 GHz
Output Power	P _{OUT1}	_	57.1	_		$V_{DD} = 50 \text{ V}, I_{DQ} = 500 \text{ mA}, P_{IN} = 46 \text{ dBm}, Freq = 2.9 \text{ GHz}$
Output Power	P _{OUT2}	_	56.9	_	dBm	$V_{DD} = 50 \text{ V}, I_{DQ} = 500 \text{ mA}, P_{IN} = 46 \text{ dBm}, Freq = 3.2 \text{ GHz}$
Output Power	P _{out3}	_	56.4	_		$V_{DD} = 50 \text{ V}, I_{DQ} = 500 \text{ mA}, P_{IN} = 46 \text{ dBm}, Freq = 3.5 \text{ GHz}$
Drain Efficiency	D _{E1}	_	69	_		$V_{DD} = 50 \text{ V}, I_{DQ} = 500 \text{ mA}, P_{IN} = 46 \text{ dBm}, Freq = 2.9 \text{ GHz}$
Drain Efficiency	D _{E2}	_	64	_	%	$V_{DD} = 50 \text{ V}, I_{DQ} = 500 \text{ mA}, P_{IN} = 46 \text{ dBm}, \text{Freq} = 3.2 \text{ GHz}$
Drain Efficiency	D _{E3}	_	60	_		$V_{DD} = 50 \text{ V}, I_{DQ} = 500 \text{ mA}, P_{IN} = 46 \text{ dBm}, Freq = 3.5 \text{ GHz}$
Power Gain	G _{P2}	_	11.1	_		$V_{DD} = 50 \text{ V}, I_{DQ} = 500 \text{ mA}, P_{IN} = 46 \text{ dBm}, Freq = 2.9 \text{ GHz}$
Power Gain	G _{P3}	_	10.9	_		$V_{DD} = 50 \text{ V}, I_{DQ} = 500 \text{ mA}, P_{IN} = 46 \text{ dBm}, \text{Freq} = 3.2 \text{ GHz}$
Power Gain	G _{P4}	_	10.4	_	dB	$V_{DD} = 50 \text{ V}, I_{DQ} = 500 \text{ mA}, P_{IN} = 46 \text{ dBm}, Freq = 3.5 \text{ GHz}$
Input Return Loss	S11	_	-7.1	_		D = 20 dD = 2.0. 2.5 CU-
Output Return Loss	S22	_	-5.8	_		P _{IN} = -20 dBm, 2.9 - 3.5 GHz
Output Mismatch Stress	VSWR	_	3:1	_	Ψ	No damage at all phase angles

Notes:

Thermal Characteristics

Parameter	Symbol	Rating	Units	Conditions
Operating Junction Temperature	T _J	224	°C	Pulse Width = 2 ms, Duty Cycle = 20%, P _{DISS} = 418 W, T _{CASE} = 57.2°C
Thermal Resistance, Junction to Case	$R_{\theta JC}$	0.4	°C/W	

¹ Scaled from PCM data

 $^{^{2}}$ Unless otherwise noted: Pulse Width = 2 ms, Duty Cycle = 20%



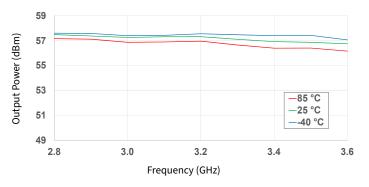


Figure 1. Output Power vs Frequency as a Function of Temperature

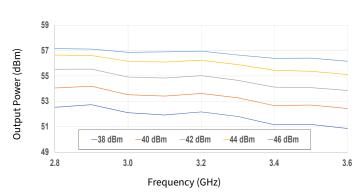


Figure 2. Output Power vs Frequency as a Function of Input Power

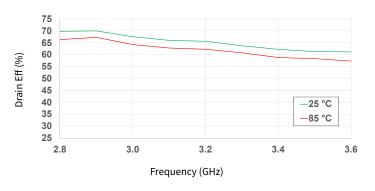


Figure 3. Drain Eff. vs Frequency as a Function of Temperature

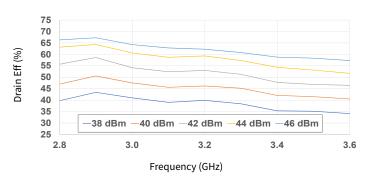


Figure 4. Drain Eff. vs Frequency as a Function of Input Power

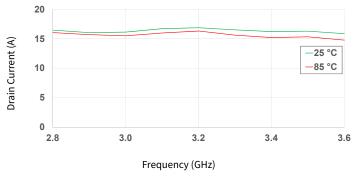


Figure 5. Drain Current vs Frequency as a Function of Temperature

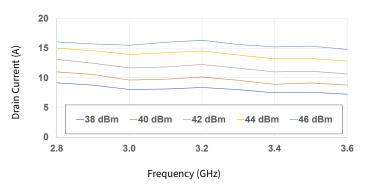


Figure 6. Drain Current vs Frequency as a Function of Input Power



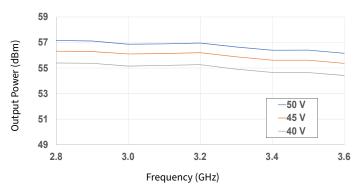


Figure 7. Output Power vs Frequency as a Function of V_D

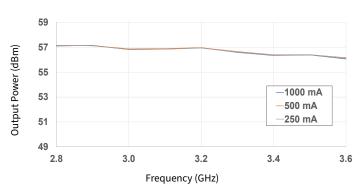


Figure 8. Output Power vs Frequency as a Function of I_{DO}

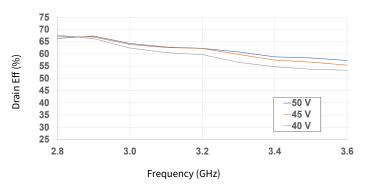


Figure 9. Drain Eff. vs Frequency as a Function of V_D

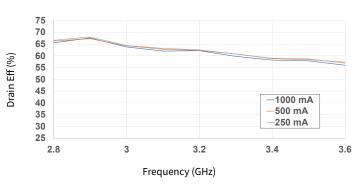


Figure 10. Drain Eff. vs Frequency as a Function of I_{DO}

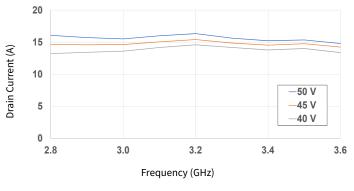


Figure 11. Drain Current vs Frequency as a Function of V_D

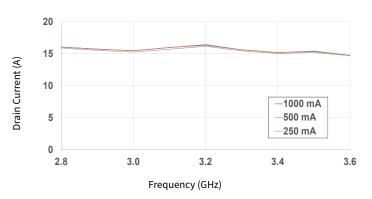


Figure 12. Drain Current vs Frequency as a Function of I_{DO}



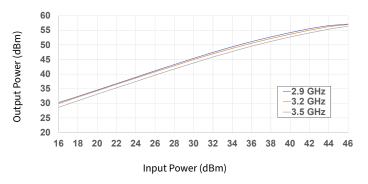


Figure 13. Output Power vs Input Power as a Function of Frequency

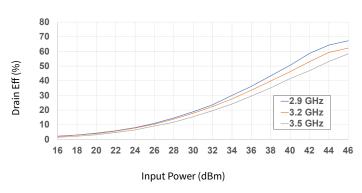


Figure 14. Drain Eff. vs Input Power as a Function of Frequency

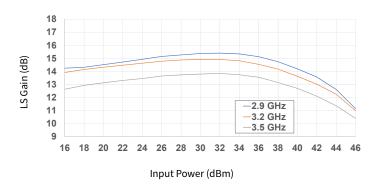


Figure 15. Large Signal Gain vs Input Power as a Function of Frequency

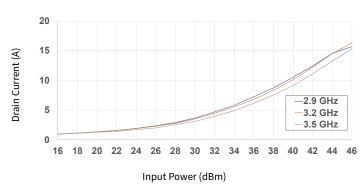


Figure 16. Drain Current vs Input Power as a Function of Frequency

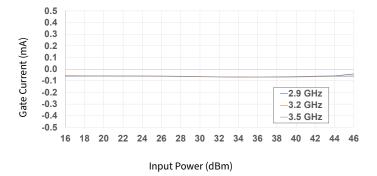


Figure 17. Gate Current vs Input Power as a Function of Frequency



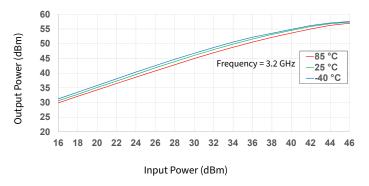


Figure 18. Output Power vs Input Power as a Function of Temperature

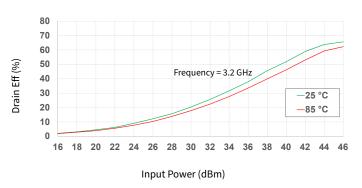


Figure 19. Drain Eff. vs Input Power as a Function of Temperature

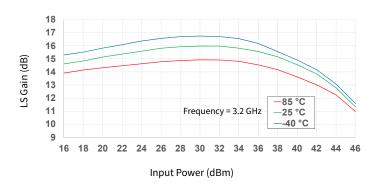


Figure 20. Large Signal Gain vs Input Power as a Function of Temperature

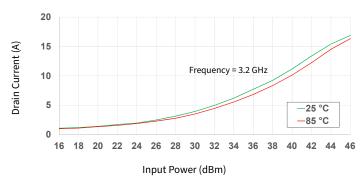


Figure 21. Drain Current vs Input Power as a Function of Temperature

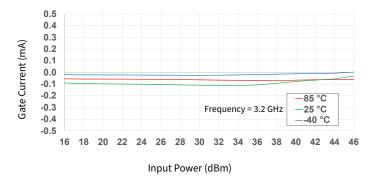


Figure 22. Gate Current vs Input Power as a Function of Temperature



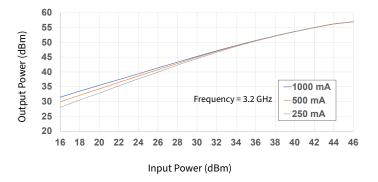


Figure 23. Output Power vs Input Power as a Function of I_{DO}

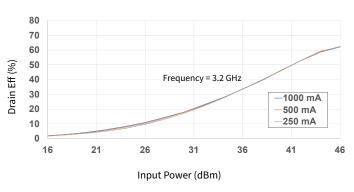


Figure 24. Drain Eff. vs Input Power as a Function of I_{DO}

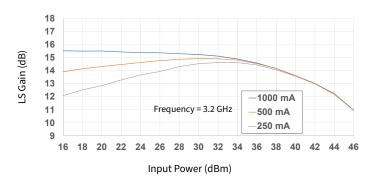


Figure 25. Large Signal Gain vs Input Power as a Function of I_{DO}

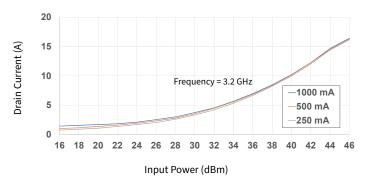


Figure 26. Drain Current vs Input Power as a Function of I_{DO}

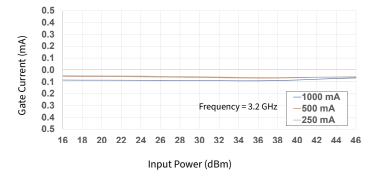


Figure 27. Gate Current vs Input Power as a Function of I_{DQ}



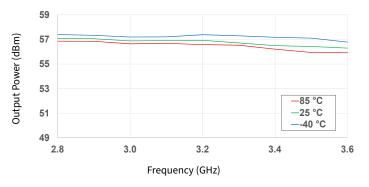


Figure 28. Output Power vs Frequency as a Function of Temperature

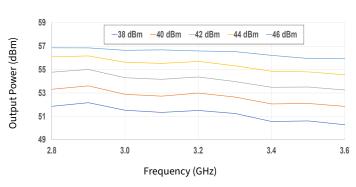


Figure 29. Output Power vs Frequency as a Function of Input Power

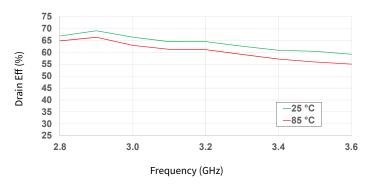


Figure 30. Drain Eff. vs Frequency as a Function of Temperature

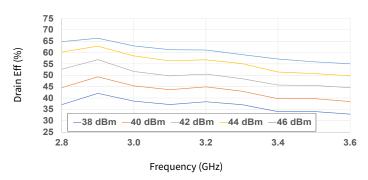


Figure 31. Drain Eff. vs Frequency as a Function of Input Power

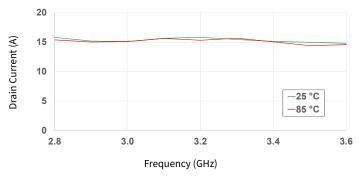


Figure 32. Drain Current vs Frequency as a Function of Temperature

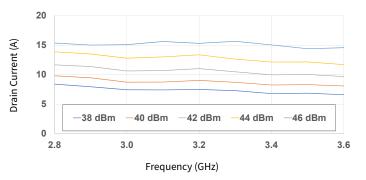


Figure 33. Drain Current vs Frequency as a Function of Input Power



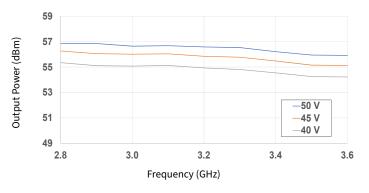


Figure 34. Output Power vs Frequency as a Function of V_D

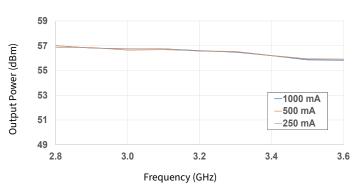


Figure 35. Output Power vs Frequency as a Function of I_{DO}

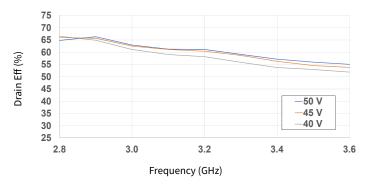


Figure 36. Drain Eff. vs Frequency as a Function of V_D

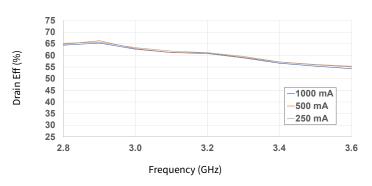


Figure 37. Drain Eff. vs Frequency as a Function of I_{DO}

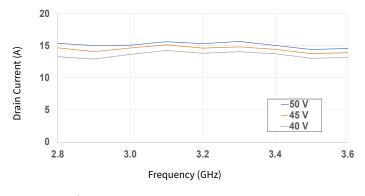


Figure 38. Drain Current vs Frequency as a Function of V_D

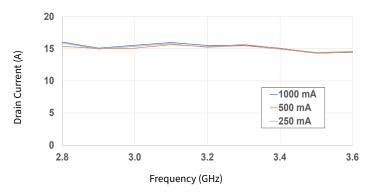


Figure 39. Drain Current vs Frequency as a Function of I_{DO}



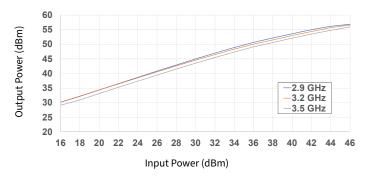


Figure 40. Output Power vs Input Power as a Function of Frequency

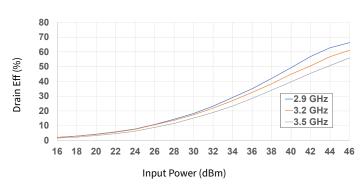


Figure 41. Drain Eff. vs Input Power as a Function of Frequency

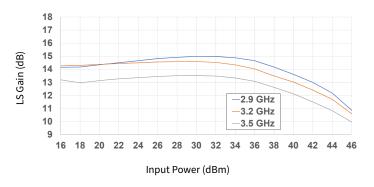


Figure 42. Large Signal Gain vs Input Power as a Function of Frequency

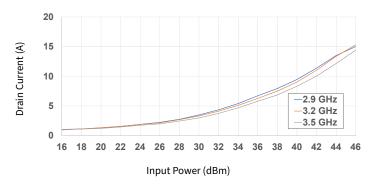


Figure 43. Drain Current vs Input Power as a Function of Frequency

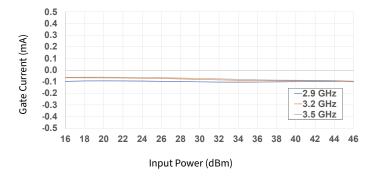


Figure 44. Gate Current vs Input Power as a Function of Frequency



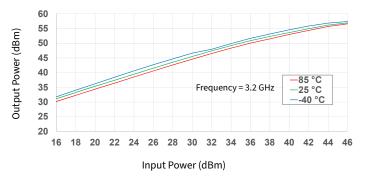


Figure 45. Output Power vs Input Power as a Function of Temperature

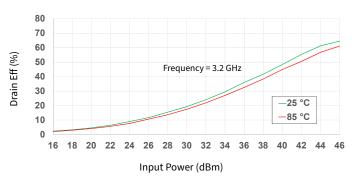


Figure 46. Drain Eff. vs Input Power as a Function of Temperature

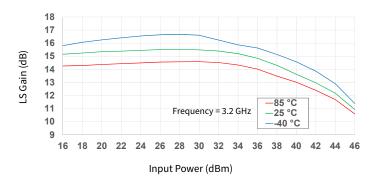


Figure 47. Large Signal Gain vs Input Power as a Function of Temperature

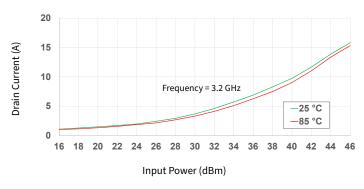


Figure 48. Drain Current vs Input Power as a Function of Temperature

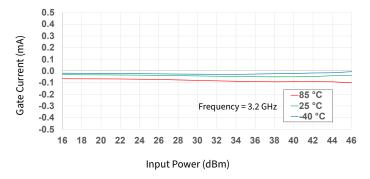


Figure 49. Gate Current vs Input Power as a Function of Temperature



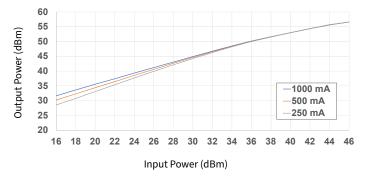


Figure 50. Output Power vs Input Power as a Function of I_{DO}

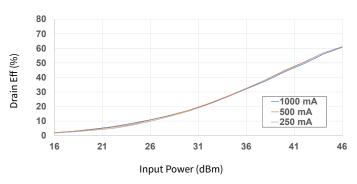


Figure 51. Drain Eff. vs Input Power as a Function of I_{DO}

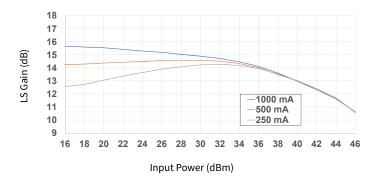


Figure 52. Large Signal Gain vs Input Power as a Function of I_{DO}

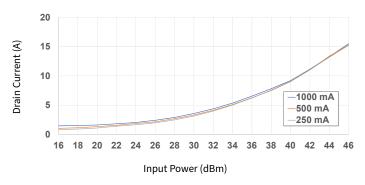


Figure 53. Drain Current vs Input Power as a Function of I_{DO}

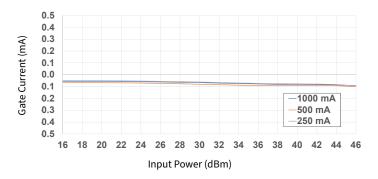


Figure 54. Gate Current vs Input Power as a Function of I_{DQ}



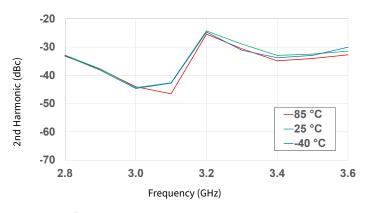


Figure 55. 2nd Harmonic vs Frequency as a Function of Temperature

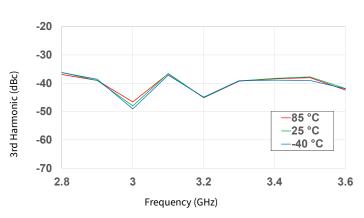


Figure 56. 3rd Harmonic vs Frequency as a Function of Temperature

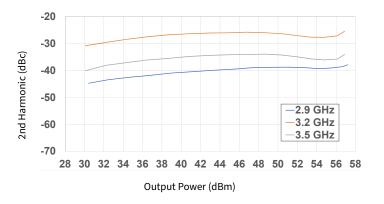


Figure 57. 2nd Harmonic vs Output Power as a Function of Frequency

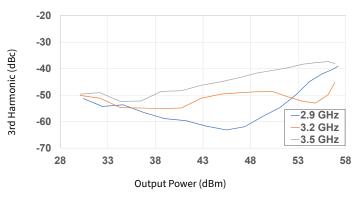


Figure 58. 3rd Harmonic vs Output Power as a Function of Frequency

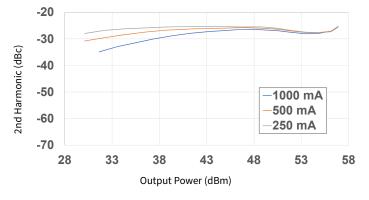


Figure 59. 2nd Harmonic vs Output Power as a Function of I_{DO}

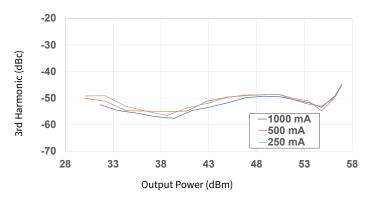


Figure 60. 3rd Harmonic vs Output Power as a Function of I_{DO}



Test conditions unless otherwise noted: $V_D = 50 \text{ V}$, $I_{DO} = 500 \text{ mA}$, $P_{IN} = -20 \text{ dBm}$, $T_{BASE} = +25 ^{\circ}\text{C}$

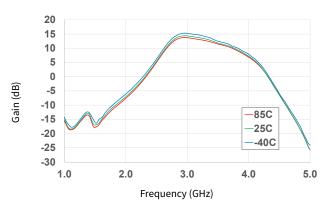


Figure 61. Gain vs Frequency as a Function of Temperature

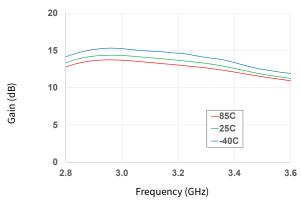


Figure 62. Gain vs Frequency as a Function of Temperature

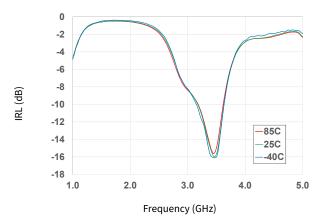


Figure 63. Input RL vs Frequency as a Function of Temperature

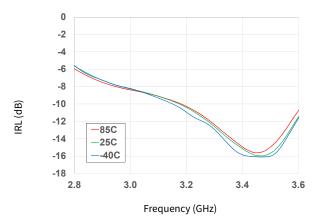


Figure 64. Input RL vs Frequency as a Function of Temperature

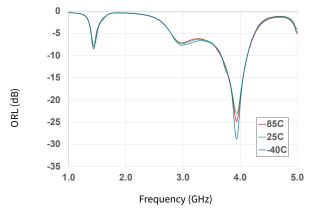


Figure 65. Output RL vs Frequency as a Function of Temperature

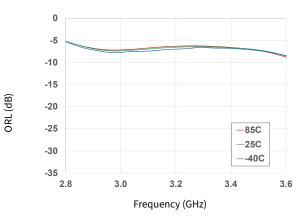


Figure 66. Output RL vs Frequency as a Function of Temperature



Test conditions unless otherwise noted: $V_D = 50 \text{ V}$, $I_{DO} = 500 \text{ mA}$, $P_{IN} = -20 \text{ dBm}$, $T_{BASE} = +25 ^{\circ}\text{C}$

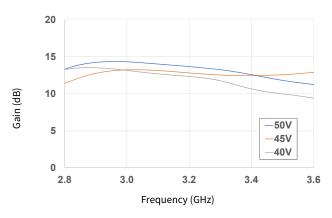


Figure 67. Gain vs Frequency as a Function of Voltage

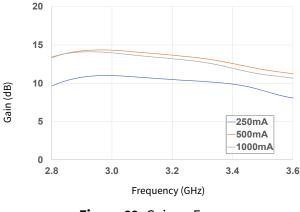


Figure 68. Gain vs Frequency as a Function of I_{DO}

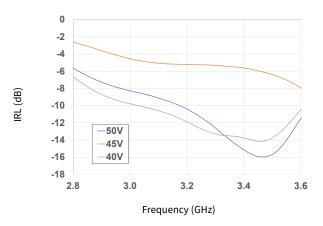


Figure 69. Input RL vs Frequency as a Function of Voltage

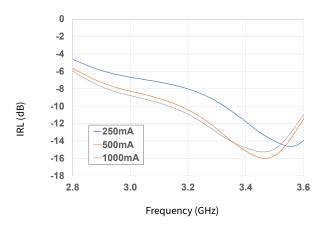


Figure 70. Input RL vs Frequency as a Function of I_{DO}

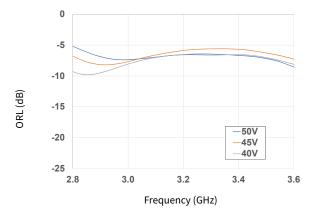


Figure 71. Output RL vs Frequency as a Function of Voltage

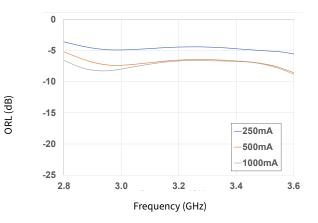
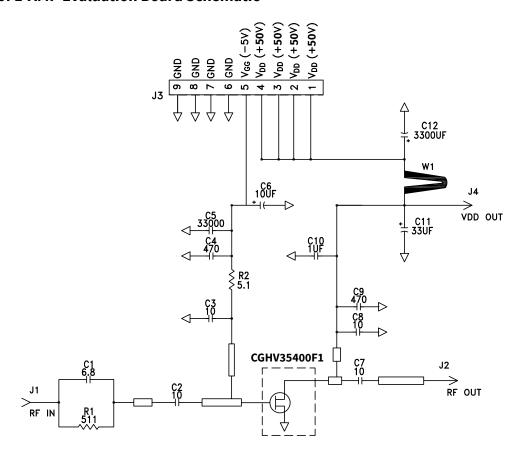


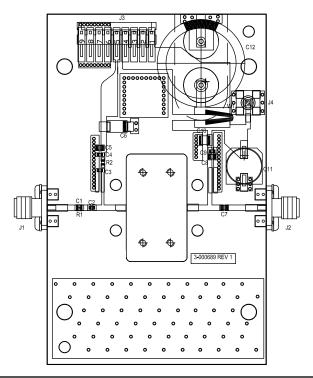
Figure 72. Output RL vs Frequency as a Function of I_{DO}



CGHV35400F1-AMP Evaluation Board Schematic



CGHV35400F1-AMP Evaluation Board Outline





CGHV35400F1-AMP Evaluation Board Bill of Materials

Designator	Description	Qty
R1	RES, 511, ohm, +/- 1%, 1/16W, 0603	1
R2	RES, 5.1, ohm, +/- 1%, 1/16W, 0603	1
C1	CAP, 6.8pF, +/-0.25%, 250V, 0603	1
C2, C7, C8	CAP, 10.0pF, +/-1%, 250V, 0805	3
C3	CAP, 10.0pF, +/-5%, 250V, 0603	1
C4, C9	CAP, 470pF, 5%, 100V, 0603, X	2
C5	CAP, 33000 pF, 0805, 100V, X7R	1
C6	CAP, 10μF, 16V, TANTALUM	1
C10	CAP, 1.0μF, 100V, 10%, X7R, 1210	1
C11	CAP, 33μF, 20%, G CASE	1
C12	CAP, 3300μF, +/-20%, 100V, ELECTROLYTIC	1
J1, J2	CONN, SMA, PANEL MOUNT JACK, FL	2
J3	HEADER, RT>PLZ, 0.1CEN LK 9POS	1
J4	CONNECTOR; SMB, Straight, JACK, SMD	1
W1	CABLE, 18 AWG, 4.2	1
	PCB, RO4350, 2.5 X 4.0 X 0.030	1
Q1	CGHV35400F1	1

Electrostatic Discharge (ESD) Classifications

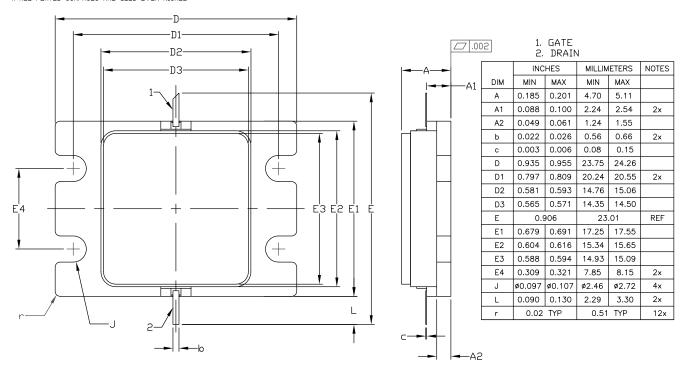
Parameter	Symbol	Class	Classification Level	Test Methodology
Human Body Model	НВМ	1B	ANSI/ESDA/JEDEC JS-001 Table 3	JEDEC JESD22 A114-D
Charge Device Model	CDM	0CB	ANSI/ESDA/JEDEC JS-002 Table 3	JEDEC JESD22 C101-C



Product Dimensions CGHV35400F1 (Package 440226)

NOTES: (UNLESS OTHERWISE SPECIFIED)

- 1. INTERPRET DRAWING IN ACCORDANCE WITH ANSI Y14.5M-2009
- 2. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF .020 BEYOND EDGE OF LID
- 3. LID MAY BE MISALIGNED TO THE BODY OF PACKAGE BY A MAXIMUM OF .008 IN ANY DIRECTION
- 4. ALL PLATED SURFACES ARE GOLD OVER NICKEL



Pin	Desc.		
1	GATE/RFIN		
2	DRAIN/RFOUT		
3	SOURCE/FLANGE		



Part Number System

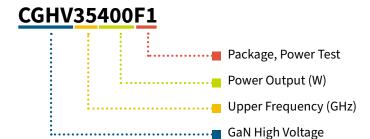


Table 1.

Parameter	Value	Units	
Lower Frequency	2.9	GHz	
Upper Frequency	3.5		
Power Output	400	W	
Package	Flange	_	

Note:

Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

Table 2.

Character Code	Code Value
Α	0
В	1
С	2
D	3
E	4
F	5
G	6
Н	7
J	8
К	9
Examples:	1A = 10.0 GHz 2H = 27.0 GHz



Product Ordering Information

Order Number	Description	Unit of Measure	Image
CGHV35400F1	GaN HEMT	Each	COMPANY
CGHV35400F1-AMP	Test board with GaN HEMT installed	Each	



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